

# LNPT<sup>™</sup> THERMOCOMP<sup>™</sup> COMPOUND PF008S

PF-1008 HS

REGION EUROPE

## DESCRIPTION

LNP THERMOCOMP PF008S compound is based on Nylon 6 resin containing 40% glass fiber. Added features of this grade include: Heat Stabilized.

GENERAL INFORMATION	
Features	Heat Stabilized, High stiffness/Strength, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polyamide 6 (Nylon 6)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Building and Construction	Building Component
Consumer	Sport/Leisure, Personal Accessory, Home Appliances, Commercial Appliance
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

## TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
<b>MECHANICAL <sup>(1)</sup></b>			
Tensile Stress, yield, 5 mm/min	182	MPa	ISO 527
Tensile Strain, break, 5 mm/min	3.9	%	ISO 527
Tensile Modulus, 1 mm/min	11500	MPa	ISO 527
Flexural Stress, yield, 2 mm/min	273	MPa	ISO 178
Flexural Modulus, 2 mm/min	10900	MPa	ISO 178
<b>IMPACT <sup>(1)</sup></b>			
Izod Impact, unnotched 80*10*4 +23°C	92	kJ/m <sup>2</sup>	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	17	kJ/m <sup>2</sup>	ISO 180/1A
<b>THERMAL <sup>(1)</sup></b>			
CTE, 23°C to 60°C, flow	1.80E-05	1/°C	ISO 11359-2
CTE, 23°C to 60°C, xflow	9.30E-05	1/°C	ISO 11359-2
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	217	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	208	°C	ISO 75/Af
<b>PHYSICAL <sup>(1)</sup></b>			
Mold Shrinkage, flow <sup>(2)</sup>	0.1 – 0.3	%	SABIC method
Density	1.47	g/cm <sup>3</sup>	ISO 1183
Water Absorption, (23°C/24hrs)	0.9	%	ISO 62-1
<b>INJECTION MOLDING <sup>(3)</sup></b>			
Drying Temperature	80	°C	

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Drying Time	4	Hrs	
Maximum Moisture Content	0.15 – 0.25	%	
Melt Temperature	265 – 275	°C	
Front - Zone 3 Temperature	275 – 290	°C	
Middle - Zone 2 Temperature	265 – 275	°C	
Rear - Zone 1 Temperature	250 – 260	°C	
Mold Temperature	80 – 95	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

## MORE INFORMATION

For curve data and CAE cards, please visit and register at <https://materialfinder.sabic-specialties.com>

## ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

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